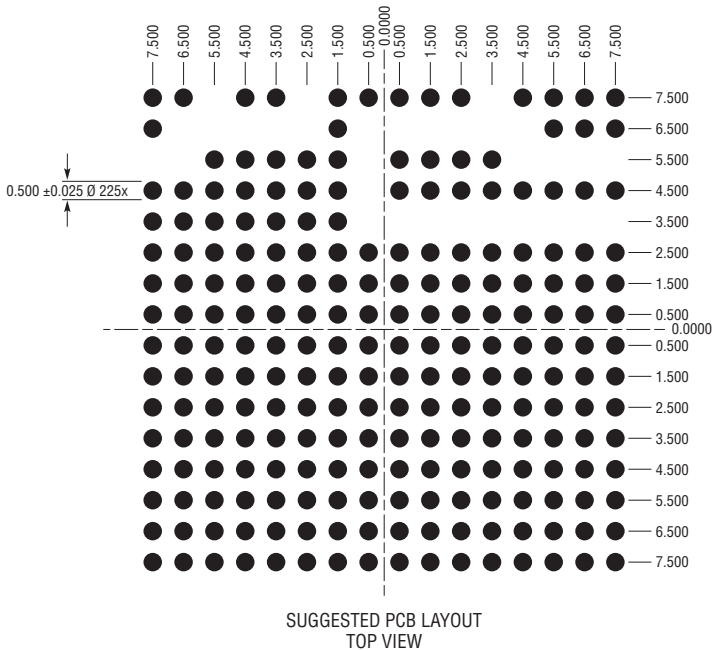
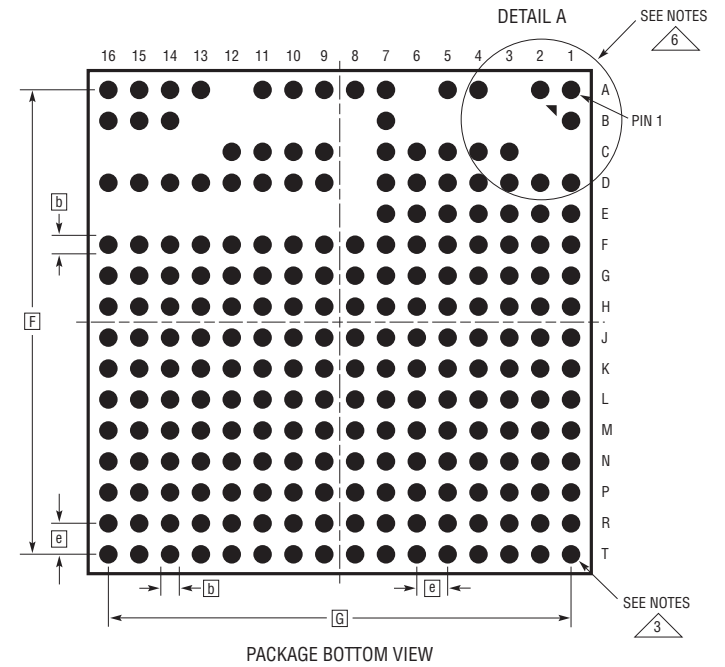
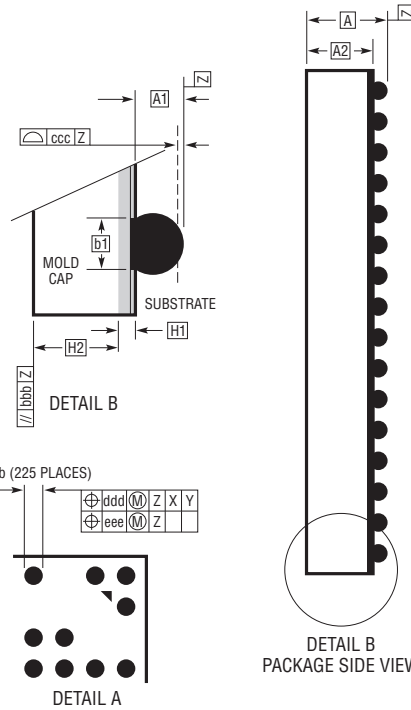
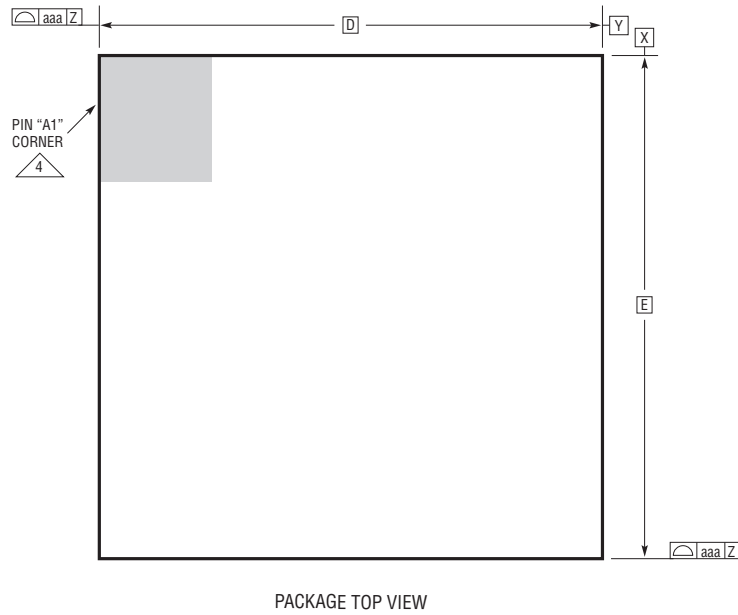


**BGA Package**  
**225-Lead (16mm × 16mm × 2.32mm)**  
 (Reference LTC DWG # 05-08-1827 Rev 0)



DIMENSIONS				
SYMBOL	MIN	NOM	MAX	NOTES
A	2.18	2.32	2.46	
A1	0.45	0.50	0.55	BALL HT
A2	1.73	1.82	1.91	
b	0.50	0.60	0.70	BALL DIMENSION
b1	0.47	0.50	0.53	PAD DIMENSION
D	16.00			
E	16.00			
e	1.00			
F	15.00			
G	15.00			
H1	0.28	0.32	0.36	SUBSTRATE THK
H2	1.45	1.50	1.55	MOLD CAP HT
aaa			0.15	
bbb			0.10	
ccc			0.20	
ddd			0.25	
eee			0.10	

TOTAL NUMBER OF BALLS: 225

NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994

2. ALL DIMENSIONS ARE IN MILLIMETERS

3 BALL DESIGNATION PER JESD MS-028 AND JEP95

4 DETAILS OF PIN #1 IDENTIFIER ARE OPTIONAL, BUT MUST BE LOCATED WITHIN THE ZONE INDICATED. THE PIN #1 IDENTIFIER MAY BE EITHER A MOLD OR MARKED FEATURE

5. PRIMARY DATUM -Z- IS SEATING PLANE

6 PACKAGE ROW AND COLUMN LABELING MAY VARY AMONG µModule PRODUCTS. REVIEW EACH PACKAGE LAYOUT CAREFULLY

